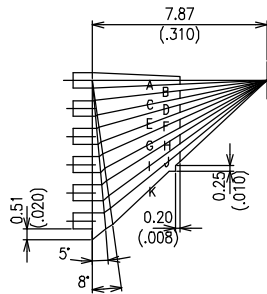


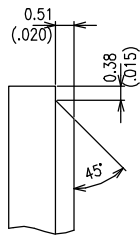
NOTES

1. MATERIALS:
 CERAMIC TO OPAQUE.90-94% Al₂O₃
 SOLDER GLASS TO BE 7583.
 MAX PULLBACK TO BE 0.25(.010)
 FROM CERAMIC EDGE.
 DIE ATTACH AREA TO BE Au . 120
 MICROINCH MIN.
 LEAD FRAME TO BE ALLOY 42 OR
 EQUIVALENT WITH ALUMINIUM
 BOND PADS. 100 MICROINCH THICK
 AND 35 MILS IN LENGTH WITH NO
 PULL BACK.
3. THERE WILL BE NO UNSUPPORTED
 BOND PADS GREATER THAN 0.25(.010)
4. ADJACENT BOND PADS MUST BE
 CO-PLANAR WITHIN 0.15(.006).
 TOTAL CO-PLANARITY NO GREATER
 THAN 0.25(.010).
5. THERE WILL BE NO NICKS. CUTS
 OR GLASS IN THE BOND RADIUS.
6. MINIMUM INTERNAL METAL
 SEPARATION TO BE 0.13(.005).

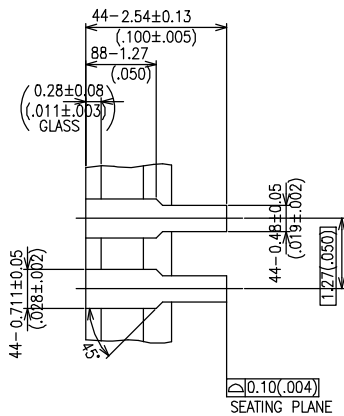
A	2.49
B	6.68
C	11.55
D	15.62
E	20.29
F	24.14
G	28.51
H	32.09
I	36.11
J	39.37
K	43.01



LEAD TIP DETAIL

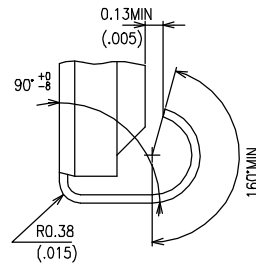


VIEW B



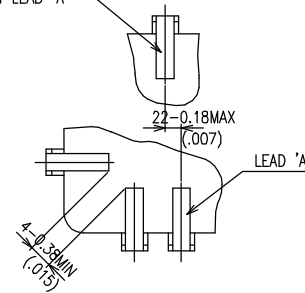
VIEW C

0.10(.004)
SEATING PLANE

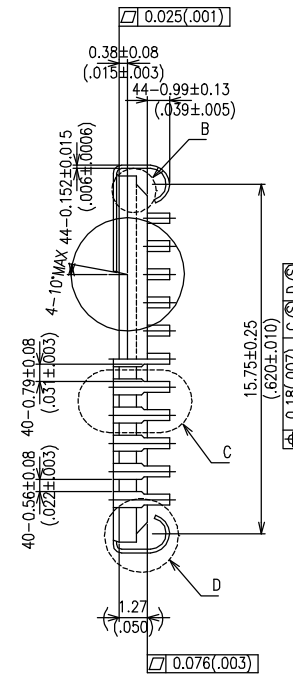
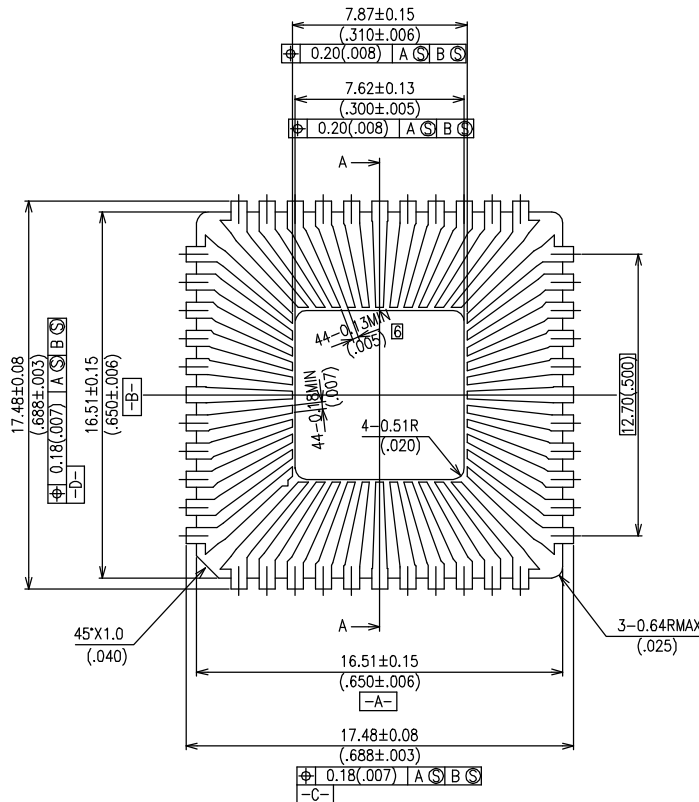


VIEW D

LEAD 'B' OPPOSITE SIDE
OF PACKAGE FROM LEAD 'A'



JEDEC TYPE



SECTION A-A

MODIFICATIONS	DATE	DRAWN	CHECKED	APPROVED

NAME
44LD QUAD CERPAC'J'(650-300)
SCALE: MATERIAL
(6 : 1)

TOLERANCES:
UNLESS OTHERWISE SPECIFIED

DRAWN	CHECKED
K.Ohtsuka	
APPROVED	DATE
	JUN.15'88

C H A N G E

KYOCERA CORPORATION

KYOTO JAPAN

DWG No.

QC-044248-J-1